


# ELECTRONIC INFORMATION DISCLOSURE STATEMENT

Electronic Version v18

Stylesheet Version v18.0

Title of Invention	WIRING STRUCTURE FOR INTEGRATED CIRCUIT WITH REDUCED INTRALEVEL CAPACITANCE						
<div>Application Number : 10/709204 </div> <div>Confirmation Number: 3203</div> <div>First Named Applicant: Richard Wise</div> <div>Attorney Docket Number: FIS920030028us1</div> <div>Art Unit: 2823</div> <div>Examiner: Julio Maldonado</div> <div>Search string: ( 6661094 ).pn</div>							
<p><b>Certification:</b> This Information Disclosure Statement was submitted under the following conditions, which satisfies the requirement under 37 CFR 1.97(e). The filer certified:</p> <p>That each item of information contained in the information disclosure statement was first cited in any communication from a foreign patent office in a counterpart foreign application not more than three months prior to the filing of the information disclosure statement.</p>							
<b>US Patent Documents</b>							
<b>Note: Applicant is not required to submit a paper copy of cited US Patent Documents</b>							
init	Cite.No.	Patent No.	Date	Patentee	Kind	Class	Subclass
8	1	6661094	2003-12-09	Morrow et al.		257	758
<b>Signature</b>							
Examiner Name				Date			
